

## Materials Declaration

<b>Package</b>	SC 70-ISOLATED BACKSIDE
<b>Body Size</b>	--
<b>LeadCount</b>	3
<b>Option</b>	Pb-free

Molding Compound			
Substance	% of Compound	Weight (g)	PPM
Silica	81.0	2.26 E-03	413345
Epoxy Resin	10.0	2.79 E-04	51030
Phenol Resin	5.0	1.39 E-04	25515
Antimony Trioxide	1.4	3.90 E-05	7144
Additive	1.1	3.07 E-05	5613
Brominated epoxy	1.0	2.79 E-05	5103
Carbon Black	0.5	1.39 E-05	2552
Subtotal	100.0	2.79 E-03	510303

Molding Compound		
Substance	PPM	Method
Lead	Not Detected	Draft IEC 62321, ICP-OES.
Cadmium	Not Detected	Draft IEC 62321, ICP-OES.
Mercury	Not Detected	Draft IEC 62321, ICP-OES.
Chromium+6	Not Detected	Draft IEC 62321, UV-VIS.
Polybrominated biphenyls (PBB)	Not Detected	Draft IEC 62321, GC-MSD.
Polybrominated Diphenyl Ethers (PBDE)	Not Detected	Draft IEC 62321, GC-MSD.

Leadframe			
Substance	% of Leadframe	Weight (g)	PPM
Iron	56.7	1.25 E-03	228458
Nickel	41.5	9.13 E-04	167214
Manganese	0.8	1.76 E-05	3223
Cobalt	0.5	1.10 E-05	2015
Silicon	0.3	6.60 E-06	1209
Chromium	0.1	2.20 E-06	403
Aluminum	0.1	2.20 E-06	403
Subtotal	100.0	2.20 E-03	402924

Die Attach Paste		
Substance	PPM	Method
Lead	Not Detected	Draft IEC 62321, ICP-OES.
Cadmium	Not Detected	Draft IEC 62321, ICP-OES.
Mercury	Not Detected	Draft IEC 62321, ICP-OES.
Chromium+6	Not Detected	Draft IEC 62321, UV-VIS.
Polybrominated biphenyls (PBB)	Not Detected	Draft IEC 62321, GC-MSD.
Polybrominated Diphenyl Ethers (PBDE)	Not Detected	Draft IEC 62321, GC-MSD.

Internal Leadframe Plating			
Substance	% of Plating	Weight (g)	PPM
Silver	100.0	4.40 E-06	805

External Leadframe Plating			
Substance	% of Plating	Weight (g)	PPM
Tin	100.0	2.00 E-04	36613

Bond Wires			
Substance	% of Wire	Weight (g)	PPM
Gold	99.9	3.00 E-05	5492

Chip			
Substance	% of Chip	Weight (g)	PPM
Doped Silicon	100.0	2.10 E-04	38444

Die Attach			
Substance	% of Die Attach	Weight (g)	PPM
Epoxy resin	46.0	1.38 E-05	2526
Silicon dioxide	46.0	1.38 E-05	2526
Curing agent & hardener	8.0	2.00 E-06	366
Subtotal	100.0	2.96 E-05	5419

Package Totals	
Weight (g)	PPM
5.46 E-03	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge  
 ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability  
 any inaccuracy of such information.



ADI Proprietary

## Materials Declaration

<b>Package</b>	SC70 - COL
<b>Body Size</b>	--
<b>LeadCount</b>	3
<b>Option</b>	NiPdAu

### Molding Compound

Substance	% of Compound	Weight (g)	PPM
Silica	87.3	2.47 E-03	466156
Phenol Resin	4.5	1.27 E-04	24029
Epoxy Resin 1	3.0	8.49 E-05	16019
Epoxy Resin 2	3.0	8.49 E-05	16019
Others	2.0	5.66 E-05	10679
Carbon Black	0.2	5.66 E-06	1068
Subtotal	100	2.83 E-03	533970

### Leadframe

Substance	% of Leadframe	Weight (g)	PPM
Copper	97.5	2.12 E-03	399590
Iron	2.35	5.10 E-05	9631
Zinc	0.12	2.61 E-06	492
Phosphorus	0.03	6.52 E-07	123
Subtotal	100	2.17 E-03	409836

### Internal Leadframe Plating/External Leadframe Plating

Substance	% of Plating	Weight (g)	PPM
Nickel	90.91	2.53 E-05	4774
Palladium	7.91	2.20 E-06	415
Gold	1.19	3.30 E-07	62
Subtotal	100.00	2.78 E-05	5251

### Bond Wires

Substance	% of Wire	Weight (g)	PPM
Gold	99.99	3.00 E-05	5660

### Chip

Substance	% of Chip	Weight (g)	PPM
Doped Silicon	100	2.10 E-04	39623

### Die Attach

Substance	% of Die Attach	Weight (g)	PPM
Epoxy Resin	31	9.30 E-06	1755
Metal Oxide	31	9.30 E-06	1755
Glycol ethers	22	6.60 E-06	1245
Silica	8	2.40 E-06	453
Curing agent & hardener	8	2.40 E-06	453
Subtotal	100	3.00 E-05	5660

### Molding Compound

Substance	PPM	Method
Lead	Not Detected	USEPA 3050B, ICP-OES.
Cadmium	Not Detected	EN1122, method B:2001, ICP-OES.
Mercury	Not Detected	USEPA 3052, ICP-OES.
Chromium+6	Not Detected	EPA 3060A/7196A, UV-VIS.
Polybrominated biphenyls (PBB)	Not Detected	EPA 3540C/3550B, GC-MS.
Polybrominated Diphenyl Ethers (PBDE)	Not Detected	EPA 3540C/3550B, GC-MS.

### Die Attach

Substance	PPM	Method
Lead	Not Detected	Draft IEC 62321, ICP-OES.
Cadmium	Not Detected	Draft IEC 62321, ICP-OES.
Mercury	Not Detected	Draft IEC 62321, ICP-OES.
Chromium+6	Not Detected	Draft IEC 62321, UV-VIS.
Polybrominated biphenyls (PBB)	Not Detected	Draft IEC 62321, GC-MSD.
Polybrominated Diphenyl Ethers (PBDE)	Not Detected	Draft IEC 62321, GC-MSD.

### Package Totals

Weight (g)	PPM
5.30 E-03	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary

## Materials Declaration

<b>Package</b>	SC 70-ISOLATED BACKSIDE
<b>Body Size</b>	--
<b>LeadCount</b>	3
<b>Option</b>	with Pb

Molding Compound			
Substance	% of Compound	Weight (g)	PPM
Silica	81.0	2.26 E-03	413345
Epoxy Resin	10.0	2.79 E-04	51030
Phenol Resin	5.0	1.39 E-04	25515
Antimony Trioxide	1.4	3.90 E-05	7144
Additive	1.1	3.07 E-05	5613
Brominated epoxy	1.0	2.79 E-05	5103
Carbon Black	0.5	1.39 E-05	2552
Subtotal	100.0	2.79 E-03	510303

Leadframe			
Substance	% of Leadframe	Weight (g)	PPM
Iron	56.7	1.25 E-03	228458
Nickel	41.5	9.13 E-04	167214
Manganese	0.8	1.76 E-05	3223
Cobalt	0.5	1.10 E-05	2015
Silicon	0.3	6.60 E-06	1209
Chromium	0.1	2.20 E-06	403
Aluminum	0.1	2.20 E-06	403
Subtotal	100.0	2.20 E-03	402924

Internal Leadframe Plating			
Substance	% of Plating	Weight (g)	PPM
Silver	100.0	4.40 E-06	805

External Leadframe Plating			
Substance	% of Plating	Weight (g)	PPM
Tin	85.0	1.70 E-04	31121
Lead	15.0	3.00 E-05	5492
Subtotal	100.0	2.00 E-04	36613

Bond Wires			
Substance	% of Wire	Weight (g)	PPM
Gold	99.9	3.00 E-05	5492

Chip			
Substance	% of Chip	Weight (g)	PPM
Doped Silicon	100.0	2.10 E-04	38444

Die Attach			
Substance	% of Die Attach	Weight (g)	PPM
Epoxy resin	46.0	1.38 E-05	2526
Silicon dioxide	46.0	1.38 E-05	2526
Curing agent & hardener	8.0	2.00 E-06	366
Subtotal	100.0	2.96 E-05	5419

Molding Compound		
Substance	PPM	Method
Lead	Not Detected	Draft IEC 62321, ICP-OES.
Cadmium	Not Detected	Draft IEC 62321, ICP-OES.
Mercury	Not Detected	Draft IEC 62321, ICP-OES.
Chromium+6	Not Detected	Draft IEC 62321, UV-VIS.
Polybrominated biphenyls (PBB)	Not Detected	Draft IEC 62321, GC-MSD.
Polybrominated Diphenyl Ethers (PBDE)	Not Detected	Draft IEC 62321, GC-MSD.

Die Attach Paste		
Substance	PPM	Method
Lead	Not Detected	Draft IEC 62321, ICP-OES.
Cadmium	Not Detected	Draft IEC 62321, ICP-OES.
Mercury	Not Detected	Draft IEC 62321, ICP-OES.
Chromium+6	Not Detected	Draft IEC 62321, UV-VIS.
Polybrominated biphenyls (PBB)	Not Detected	Draft IEC 62321, GC-MSD.
Polybrominated Diphenyl Ethers (PBDE)	Not Detected	Draft IEC 62321, GC-MSD.

Package Totals	
Weight (g)	PPM
<b>5.46 E-03</b>	<b>1000000</b>

Note: The information provided in this declaration are true to the best of ADI's knowledge  
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability  
any inaccuracy of such information.



ADI Proprietary